

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:
 - a semiconductor package including a first main surface, a second main surface provided opposite to the first main surface, a first terminal provided at said first main surface, a second terminal provided at said
 - 5 second main surface, and a semiconductor element;
 - a substrate having a third main surface opposing said first main surface, a fourth main surface provided opposite to said third main surface, a third terminal contacting said first terminal, and a fourth terminal provided at said fourth main surface;
 - 10 a metal substrate having a fifth main surface opposing said second main surface and electrically connected to said second terminal and a sixth main surface provided opposite to said fifth main surface; and
 - a metal fixing member contacting said sixth main surface to position said metal substrate,
 - 15 said substrate being provided with a hole passing through said substrate, and
 - a portion of said fixing member being inserted into said hole, and a tip of said fixing member contacting said fourth terminal.
2. The semiconductor device according to claim 1, wherein said semiconductor package is a flip chip type semiconductor package.
3. The semiconductor device according to claim 1, wherein said semiconductor package is a wire bonding type semiconductor package.